

NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCE20P45Q uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

Application

- Load switch
- Battery protection

100% UIS TESTED! 100% ΔVds TESTED!

General Features

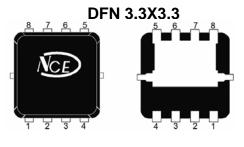
V_{DS} =-20 V,I_D =-45A

 $R_{DS(ON)}$ < 7m Ω @ V_{GS} =-4.5V

 $R_{DS(ON)}$ < 9m Ω @ V_{GS} =-2.5V

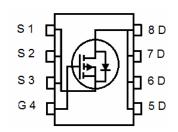
 $R_{DS(ON)}$ < 12m Ω @ V_{GS} =-1.8V

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation



Top View

Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE20P45Q	NCE20P45Q	DFN 3.3x3.3-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±10	V
Drain Current-Continuous	I _D	-45	А
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	-35	Α
Pulsed Drain Current	I _{DM}	-200	Α
Maximum Power Dissipation	P _D	80	W
Single pulse avalanche energy (Note 5)	E _{AS}	320	mJ
Derating factor		0.64	W/°C
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	R _{θJC}	1.6	°C/W	
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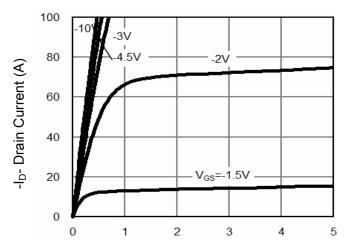
Electrical Characteristics (T_C=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			1			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-16V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			1	ı		
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=-250\mu A$	-0.4	-0.6	-1.0	V
		V _{GS} =-4.5V, I _D =-20A	-	5.8	7	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-2.5V, I _D =-20A	-	7.2	9	mΩ
	V _{GS} =-1.8V, I _D =-20A			9	12	
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-20A	80	-	-	S
Dynamic Characteristics (Note4)			1			
Input Capacitance	C_{lss}	V _{DS} =-10V,V _{GS} =0V,	-	7177	-	PF
Output Capacitance	C _{oss}		-	863	-	PF
Reverse Transfer Capacitance	$C_{\sf rss}$	F=1.0MHz	-	656	-	PF
Switching Characteristics (Note 4)			1			•
Turn-on Delay Time	$t_{d(on)}$		-	20	-	nS
Turn-on Rise Time	t _r	V_{DD} =-10V, R_{GEN} =3 Ω	-	55	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-4.5 V , R_L =0.5 Ω	-	100	-	nS
Turn-Off Fall Time	t _f		-	35	-	nS
Total Gate Charge	Q_g)/ 40\/ I 00A	-	63.5	-	nC
Gate-Source Charge	Q_{gs}	V_{DS} =-10V, I_{D} =-20A, V_{GS} =-4.5V	-	10	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} =-4.5V	-	18	-	nC
Drain-Source Diode Characteristics			1	•		•
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =-20A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-45	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = -20A	-	70	-	nS
Reverse Recovery Charge	di/dt = 100A/µs ^(Note3)		-	60	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD			y LS+LD)	

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- **5. 5.** E_{AS} condition: Tj=25 $^{\circ}\text{C}$,V_{DD}=-10V,V_G=-10V,L=0.5mH,Rg=25 Ω

Typical Electrical and Thermal Characteristics (Curves)



-Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics

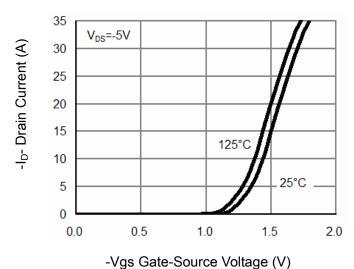


Figure 2 Transfer Characteristics

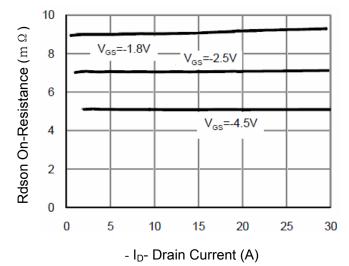


Figure 3 Rdson- Drain Current

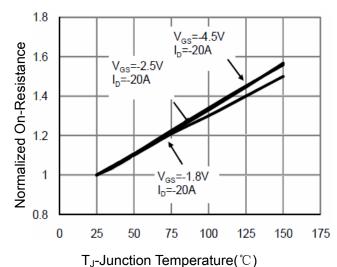
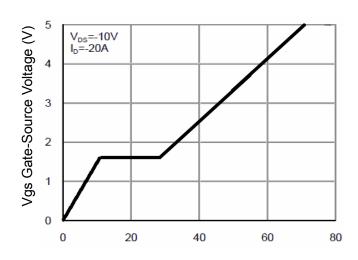


Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)
Figure 5 Gate Charge

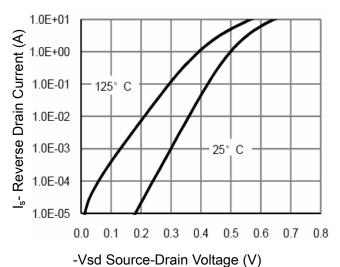


Figure 6 Source- Drain Diode Forward



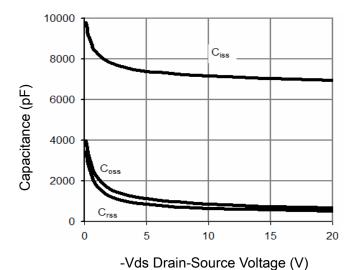


Figure 7 Capacitance vs Vds

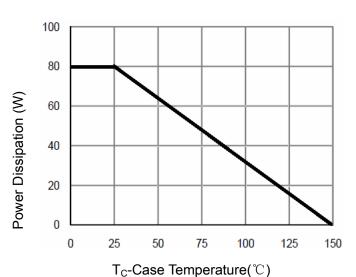


Figure 9 Power De-rating

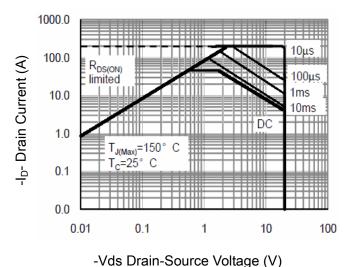


Figure 8 Safe Operation Area

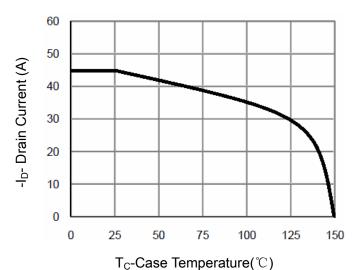
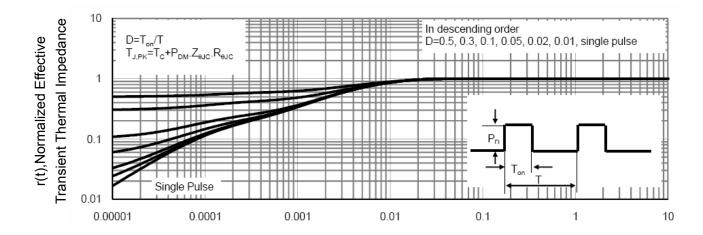


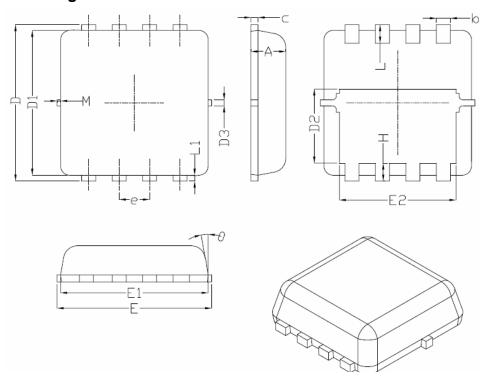
Figure 10 Current De-rating



Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

DFN3.3X3.3 EP Package Information



	T				
CVMDOI	DIMENSIONAL REQMTS				
SYMBOL	MIN	NOM	MAX		
A	0.70	0.75	0.80		
b	0.25	0.30	0.35		
c	0.10	0.15	0.25		
D	3.25	3.35	3.45		
D1	3.00	3.10	3.20		
D2	1.48	1.58	1.68		
D3		0.13			
E	3.20	3.30	3.40		
E1	3.00	3.15	3.20		
E2	2.39	2.49	2.59		
e	0.65BSC				
H	0.30	0.39	0.50		
L	0.30	0.40	0.50		
L1		0.13			
θ		10°	12°		
M	*	*	0.15		
* Not specified					

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